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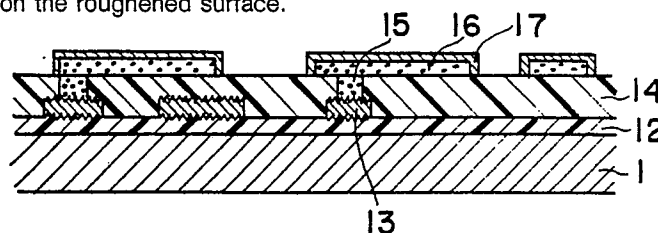
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**Multilayer printed wiring board and method for producing the same.**

A multilayer printed wiring board produced by buildup process. A first layer printed wiring pattern (13) is formed on a metal core (11) through a first insulation laminate (12), and a second layer printed wiring pattern (16) is formed on the first layer printed wiring pattern through through-studs (15) and a second insulation laminate (14). The surface of the first layer printed wiring pattern (13) is roughened and the through studs (15) are formed by buildup process a conductive paste on the roughened surface.



**Fig. 1**



DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl.4)
A	EP-A-0 048 992 (TOKYO SHIBAURA DENKI K.K.) * figures 1-4; page 5, line 12 - page 10, line 13 *	1,2,4-11,16,18,20	H 05 K 3/44 H 05 K 3/46 H 05 K 3/42
A	US-A-3 264 402 (J. M. SHAHEEN et al.) * figures 1A-F; column 2, line 58 - column 6, line 26 *	1-21	
A	US-A-4 492 730 (N. OISHI et al.) * figures 1,2; column 2, line 36 - column 5, line 3 *	1-11,20-26	
			TECHNICAL FIELDS SEARCHED (Int. Cl.4)
			H 05 K 1/00 H 05 K 3/00
The present search report has been drawn up for all claims			
Place of search BERLIN		Date of completion of the search 13-06-1989	Examiner HAHN G
<p><b>CATEGORY OF CITED DOCUMENTS</b></p> <p>X : particularly relevant if taken alone  Y : particularly relevant if combined with another document of the same category  A : technological background  O : non-written disclosure  P : intermediate document</p> <p>T : theory or principle underlying the invention  E : earlier patent document, but published on, or after the filing date  D : document cited in the application  L : document cited for other reasons</p> <p>.....  &amp; : member of the same patent family, corresponding document</p>			